

The Top Assisting Partner in the **AI Supply Chain**

C SUN Q2 Investor's meeting

A **G2C+** Alliance Company
T STRATEGY ALLIANCE

Forward-looking Statement



- Information included in this presentation that are not historical in nature are "forward-looking statements". C Sun cautions readers that forward looking statements are based on C Sun's reasonable knowledge and current expectations and are subject to various risks and uncertainties.
- Actual results may differ materially from those contained in such forward-looking statements for a variety of reasons including without limitation, risks associated with demand and supply change, manufacturing and supply capacity, design in, time to market, market competition, industrial cyclicity, customer's financial condition, exchange rate fluctuation, legal actions, amendments of the laws and regulations, global economy change, natural disasters, and other unexpected events which may disrupt C Sun's business and operations.
- Accordingly, readers should not place reliance on any forward-looking statements. Except as required by law. C Sun undertakes no obligation to update any forward-looking statement, whether as a result of new information, future events, or otherwise.

Computex 2026 | NVIDIA GTC Keynote Backdrop



G2C+ Alliance



2026
Partner



Speech topic :
Accelerating Industrial Engineering:
From Product Design to Manufacturing
in the AI Supercomputing Era

NVIDIA & 台積電





NVIDIA

2026
Partner

G2C+ Alliance: The Platform Advantage

Control (東捷)

Laser Application (雷射應用)
Sputtering & Dry Etching
(真空濺鍍 & 乾蝕刻)

GMM (均華)

- Die Attach (黏晶)
- Chip Sorter (揀晶)

2,400+

聯盟總人數
(Total Alliance Workforce)

900+

研發人員
(R&D Personnel)

© Sun (志聖)

- Thermal (熱)
- Bonder (壓合)
- Lamination (貼膜)
- Wet Process (濕製程)
- Peeling (撕膜)
- UV/Plasma (光/電漿)

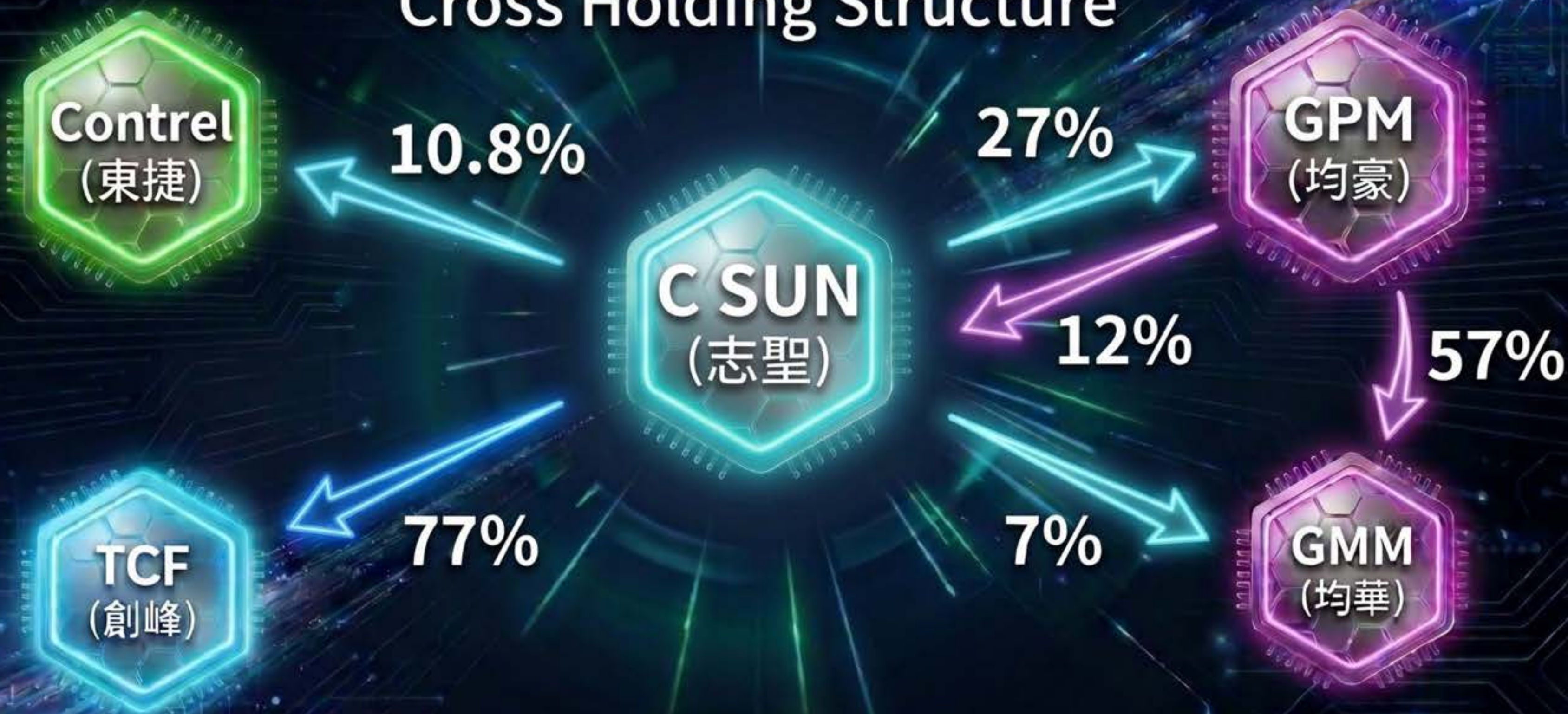
GPM (均豪)

- AOI (檢測)
- Metrology (量測)
- Grinding (研磨)
- Polishing (拋光)



G2C+ Strategy Alliance

Cross Holding Structure



TAIWAN SEMICONDUCTOR STRATEGIC CORRIDOR

Connecting Taiwan's Semiconductor Manufacturing Ecosystem

CUSTOMER CLUSTERS

- Longtan
- Hsinchu Science Park
- Central Taiwan Science Park
- Chiayi Science Park
- Southern Taiwan Science Park
- Kaohsiung Bridgehead Science Park
- Kaohsiung

TAIWAN SEMICONDUCTOR CORRIDOR

From North to South,
Powering Global Innovation



CO-DEVELOPMENT NETWORK

- ✓ On-Site Service
- ✓ Zero-Time-Difference Support
- ✓ Joint Development



PRODUCTION RESILIENCE

- ✓ Flexible Capacity
- ✓ Fast Response
- ✓ Supply Chain Resilience

G2C+ ALLIANCE MEMBERS

- CSUN
- GPM
- GMM
- Contrel



SPEED

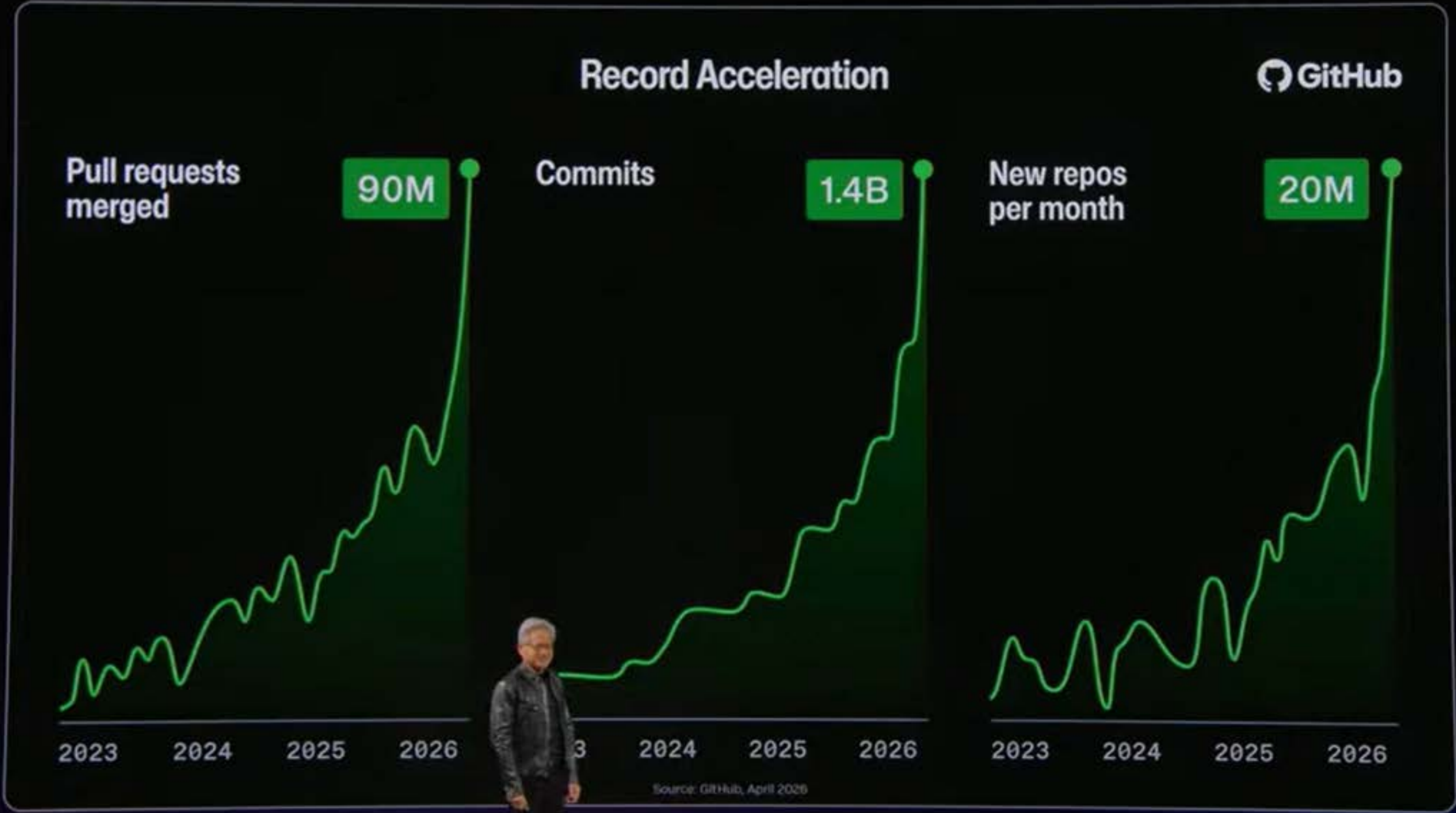


INTEGRATION



INNOVATION

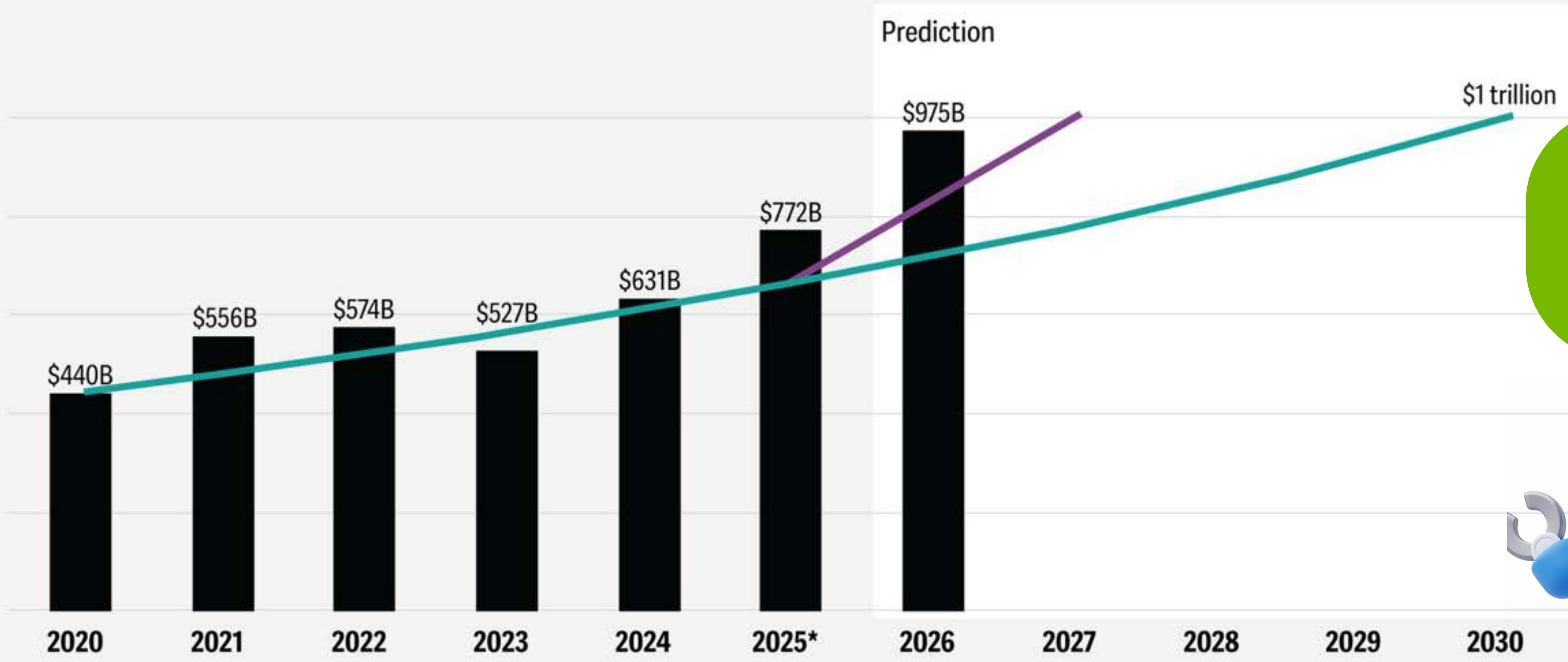
ONE ALLIANCE • ONE GOAL



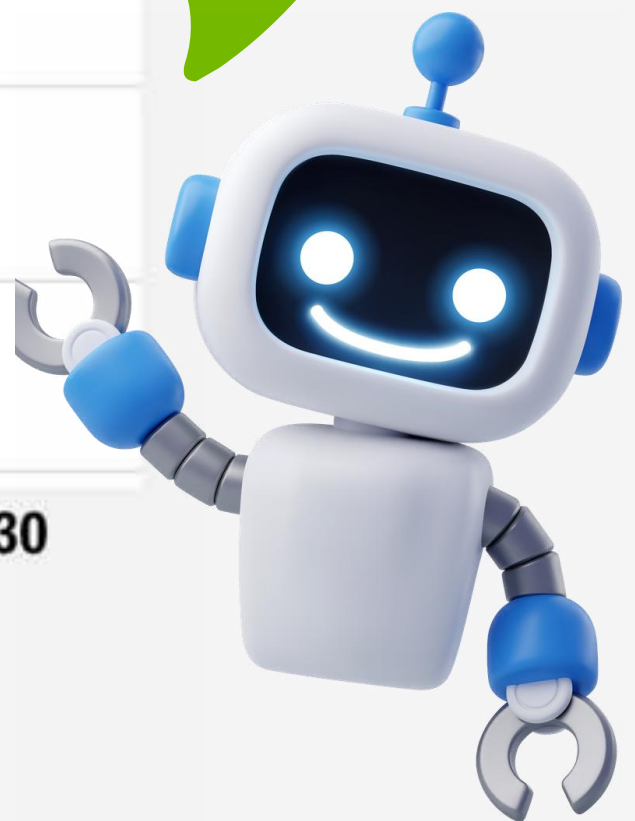
The global semiconductor market is now expected to become a \$1 trillion industry by 2027

The path to \$1 trillion in semiconductor revenues, US\$

● WSTS actuals, estimates, and predictions ● Industry revenue slope (moderate scenario) ● Industry revenue slope (optimistic scenario)



IDC:
Reaching
\$1.75T by
2030



Note: * = estimate.

Source: Deloitte analysis and extrapolation based on data from World Semiconductor Trade Statistics (WSTS).

AI Infrastructure 2.0

The Bottleneck Moves to Physics



CoWoS Size

3.3x → 14x+

2024

2029+



Power

1400W → 6000W → 15,360W

2025

2029

2032

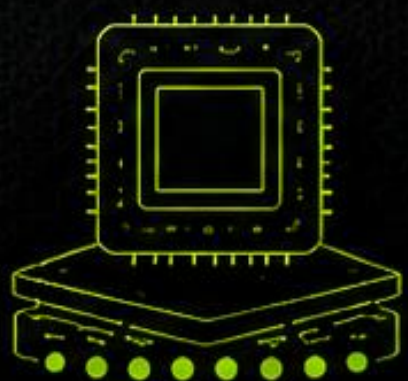


Compute

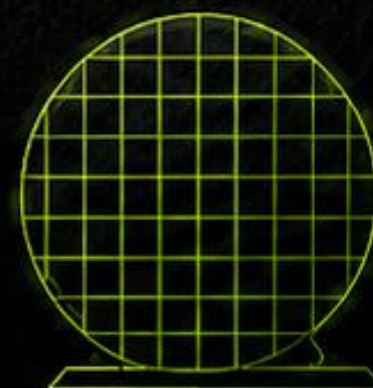
→ **Physical Scaling**

Foundry / OSAT Opportunity

Advanced Packaging = First Bottleneck



OSAT 2026
Advanced Packaging
CapEx ↑
(CoWoS / BSM / PLP)



Foundry 2026
Advanced Packaging
CapEx ↑
(CoWoS)



2024
3.3x reticle



2026
5.5x reticle



2027
9.5x reticle



Foundry: CoW / SoIC / WMCM

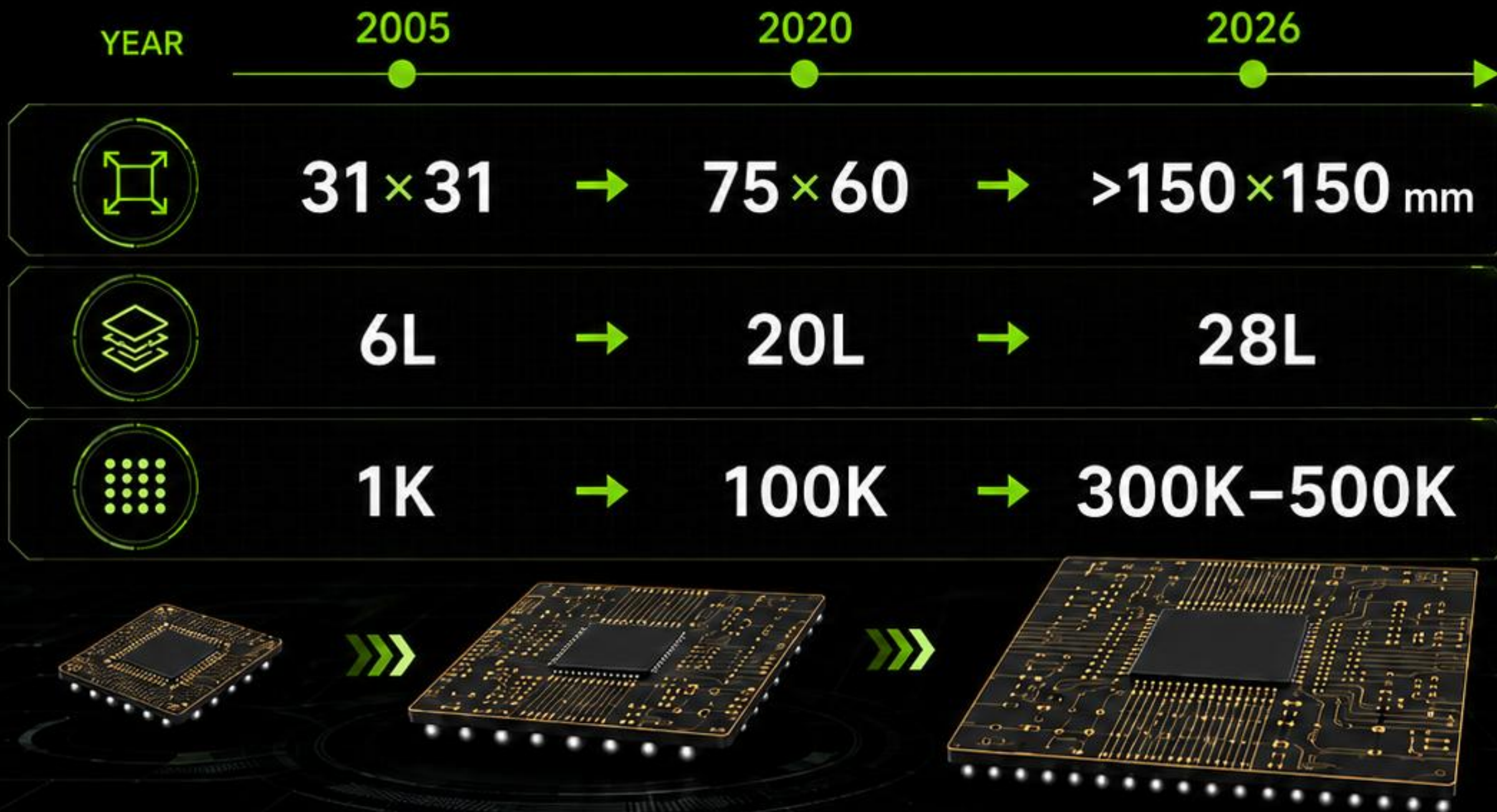


OSAT: oS / BSM / PLP

Foundry continues advanced packaging expansion;
OSAT accelerates 2026 capacity build-out for downstream advanced packaging demand.

IC Substrate Scaling

Bigger. Thicker. **Denser.**



KEY POINTS



Larger body size



Higher layer count



Higher bump density



C SUN OPPORTUNITY

- ABF lamination
- Dry film lamination for circuit patterning
- Peeling of ABF and dry-film protective layers

Board-Level Scaling

More Layers. More Critical Process Control.

1 2022-2024 |
16-26L PCB



通用伺服器 / 網通 / 工控

2 2025-2026 |
iHDI / RPCB Adoption



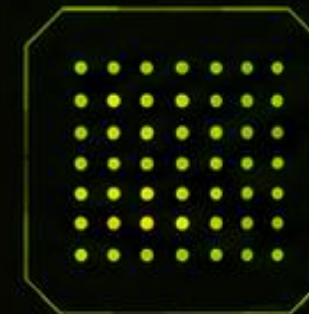
AI 伺服器 / 儲存 / 交換器

3 2026-2027 |
28-36L+ / 44L+



AI/HPC 伺服器 / mSAP / 加速器

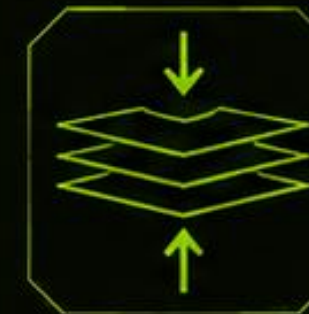
Layer Count ↑ → Process Complexity ↑
Dry Film Lamination for Circuit Patterning



均勻性



對位



應力控制

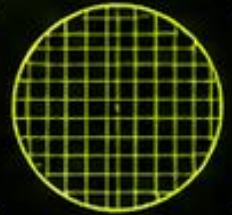


搬送穩定性

Uniformity / Alignment / Stress / Handling

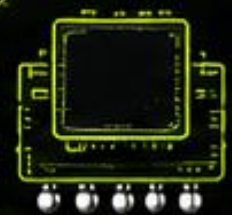
C SUN Full Spectrum Coverage

Foundry + OSAT + Advanced PCB



Foundry

CoWoS / SoIC /
WMCM / CoPoS / COUPE



OSAT

oS / BSM / CoW /
CoWoP / EMIB / PLP



Advanced PCB

IC Substrate / HDI /
CoWoP / EMIB



2024
3.3x Reticle



2028
14x Reticle



2029+
>14x Reticle



Scaling toward
larger package
architectures

CoPoS / FoPLP
Signal

Technology Roadmap

Process Coverage

Future Process Demand



Thermal



Lamination



Peeling



Bonder



Automation

Latest Financial Performance

49.5%

Q1 毛利率 (GM%)
創歷史新高



Q1 毛利率 (GM%)
創歷史新高

+76.06%

2026 Jan~May Rev. YoY
累計營收 YoY



2026 Jan~May Rev. YoY
累計營收 YoY

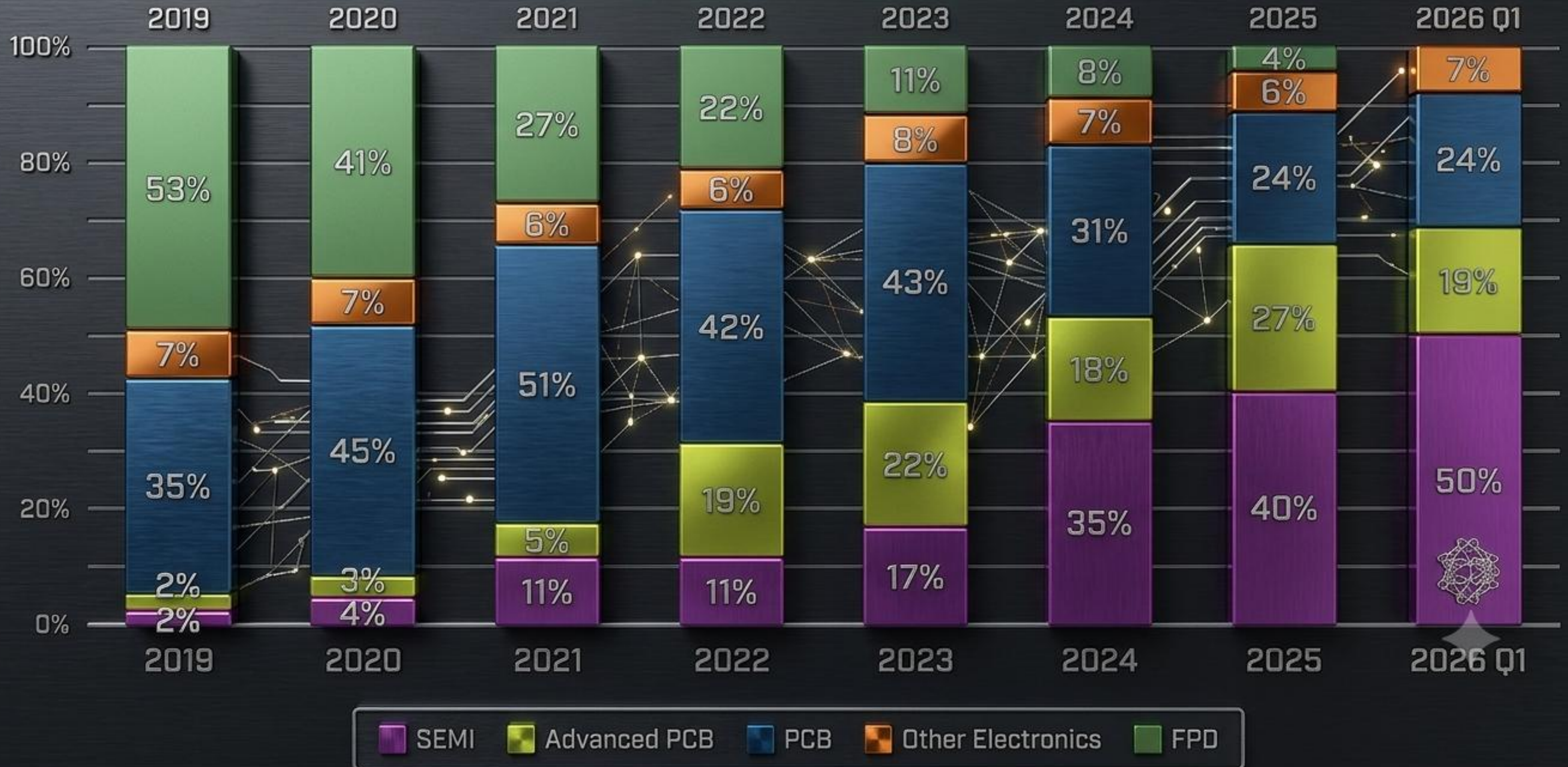
+200%

Q1 EPS YoY
Q1 EPS NT\$ 3.06



Q1 EPS YoY
Q1 EPS NT\$ 3.06

Revenue Composition



Corporate Governance

Top 5%

Listed Companies

3-Year Improvement



Governance



Board



Transparency



Sustainability



Shareholders



Risk Control



Organizational Upgrade for **Long-Term Value**

C SUN Joins Key Indices and Earns CDP Recognition

Advancing ESG Excellence, Strengthening Sustainable Competitiveness

Included in the Following Indices



MSCI
Small Cap Indexes

MSCI Small Cap Indexes



Taiwan GEM Index
(Taiwan Stock Exchange)



Taiwan Mid Cap 100 Index
(Taiwan Stock Exchange)



Taiwan Technology Index
(Taiwan Stock Exchange)



In 2025, C SUN completed
the CDP Climate Change Questionnaire

Achieved a B- Score

RATING

B-



Good Governance



Environmental Sustainability



Social Responsibility

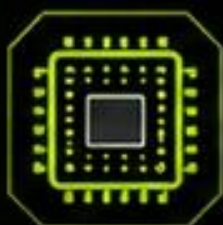
Driving a Sustainable Future Together

LONG-CYCLE GROWTH MODEL

Scale Up + Scale Out in the AI Infrastructure Decade

Scale Up

Installed Base Upgrade



Package Size ↑



Layer Count ↑



Thermal Complexity ↑



Existing process stations evolve with AI compute scaling

Scale Out

New Process Expansion



Co-design



Co-development



Core Technology Reuse



Core know-how extends into next-generation processes



AI Demand
Creates the Cycle

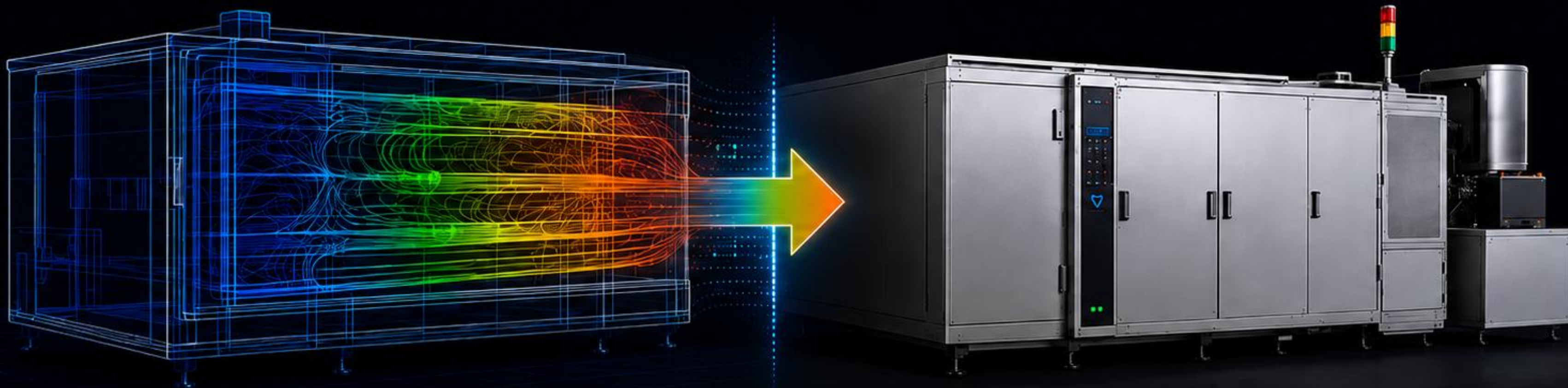


AI Complexity
Extends the Cycle



C SUN
Captures the Equipment Upgrade Cycle

Design in Virtual. Build in Reality.



Process Target



Physics + AI



Virtual Design



Physical Build



First-Time Right



Less Iteration



Lower Risk



Faster Ramp



Simulation-first in Omniverse, **Shifting Left**

***c sun*志聖**

謝謝各位 THANK YOU

攜手共創 AI 基礎建設的無限未來

BUILDING THE LIMITLESS FUTURE OF AI INFRASTRUCTURE TOGETHER

